

DATA SHEET

74LVC2G07

Buffers with open-drain outputs

Product specification
Supersedes data of 2004 Mar 19

2004 Sep 08

Buffers with open-drain outputs

74LVC2G07

FEATURES

- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant input/output for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
 - JESD8-7 (1.65 V to 1.95 V)
 - JESD8-5 (2.3 V to 2.7 V)
 - JESD8B/JESD36 (2.7 V to 3.6 V).
- –24 mA output drive ($V_{CC} = 3.0$ V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- ESD protection:
 - HBM EIA/JESD22-A114-B exceeds 2000 V
 - MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from –40 °C to +85 °C and –40 °C to +125 °C.

DESCRIPTION

The 74LVC2G07 is a high-performance, low-power, low-voltage, Si-gate CMOS device superior to most advanced CMOS compatible TTL families.

Input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

Schmitt trigger action at all inputs makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using I_{off} . The I_{off} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The 74LVC2G07 provides two non-inverting buffers.

The output of the device is an open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25$ °C.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PLZ}/t_{PZL}	propagation delay input nA to output nY	$V_{CC} = 1.8$ V; $C_L = 30$ pF; $R_L = 1$ k Ω	3.5	ns
		$V_{CC} = 2.5$ V; $C_L = 30$ pF; $R_L = 500$ Ω	2.4	ns
		$V_{CC} = 2.7$ V; $C_L = 50$ pF; $R_L = 500$ Ω	2.3	ns
		$V_{CC} = 3.3$ V; $C_L = 50$ pF; $R_L = 500$ Ω	2.6	ns
		$V_{CC} = 5.0$ V; $C_L = 50$ pF; $R_L = 500$ Ω	1.5	ns
C_I	input capacitance		2.5	pF
C_{PD}	power dissipation capacitance per gate	$V_{CC} = 3.3$ V; notes 1 and 2	6.5	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

N = total load switching outputs;

$\sum(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

2. The condition is $V_I = \text{GND}$ to V_{CC} .

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FUNCTION TABLE

See note 1.

INPUT		OUTPUT	
nA		nY	
L		L	
H		Z	

Note

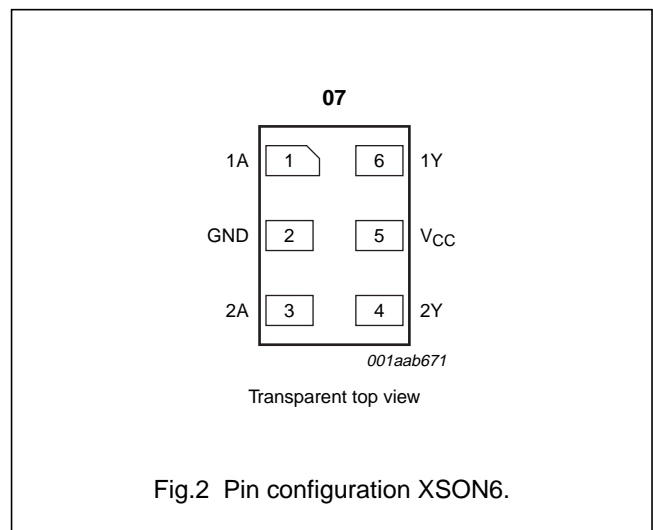
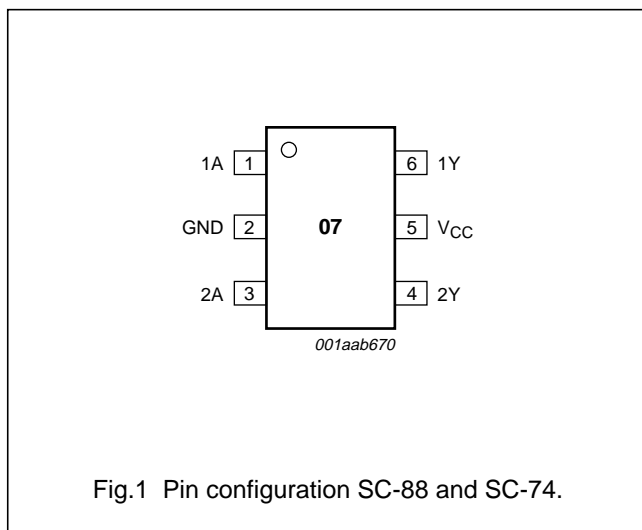
1. H = HIGH voltage level;
 L = LOW voltage level;
 Z = high-impedance OFF-state.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE					
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING
74LVC2G07GW	-40 °C to +125 °C	6	SC-88	plastic	SOT363	V7
74LVC2G07GV	-40 °C to +125 °C	6	SC-74	plastic	SOT457	V07
74LVC2G07GM	-40 °C to +125 °C	6	XSON6	plastic	SOT886	V7

PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	GND	ground (0 V)
3	2A	data input
4	2Y	data output
5	V _{CC}	supply voltage
6	1Y	data output



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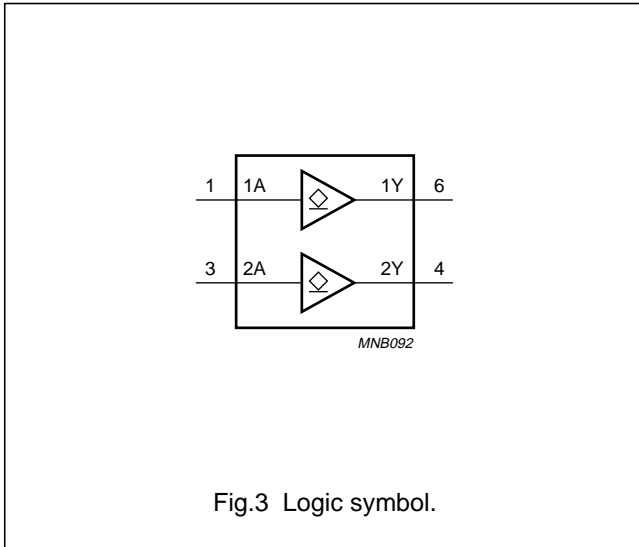


Fig.3 Logic symbol.

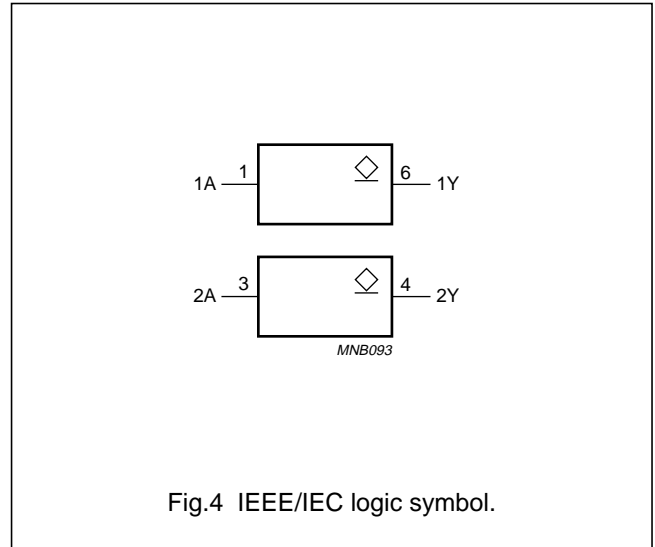


Fig.4 IEEE/IEC logic symbol.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage		1.65	5.5	V
V _I	input voltage		0	5.5	V
V _O	output voltage	active mode	0	V _{CC}	V
		V _{CC} = 0 V; Power-down mode	0	5.5	V
T _{amb}	operating ambient temperature		-40	+125	°C
t _r , t _f	input rise and fall times	V _{CC} = 1.65 V to 2.7 V	0	20	ns/V
		V _{CC} = 2.7 V to 5.5 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input diode current	V _I < 0 V	-	-50	mA
V _I	input voltage	note 1	-0.5	+6.5	V
I _{OK}	output diode current	V _O < 0 V	-	-50	mA
V _O	output voltage	active mode; notes 1 and 2	-0.5	+6.5	V
		Power-down mode; notes 1 and 2	-0.5	+6.5	V
I _O	output source or sink current	V _O = 0 V to 6.5 V	-	50	mA
I _{CC} , I _{GND}	V _{CC} or GND current		-	±100	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	power dissipation	T _{amb} = -40 °C to +125 °C	-	300	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. When V_{CC} = 0 V (Power-down mode), the output voltage can be 5.5 V in normal operation.

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DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V _{CC} (V)				
T _{amb} = -40 °C to +85 °C; note 1							
V _{IH}	HIGH-level input voltage		1.65 to 1.95	0.65 × V _{CC}	–	–	V
			2.3 to 2.7	1.7	–	–	V
			2.7 to 3.6	2.0	–	–	V
			4.5 to 5.5	0.7 × V _{CC}	–	–	V
V _{IL}	LOW-level input voltage		1.65 to 1.95	–	–	0.35 × V _{CC}	V
			2.3 to 2.7	–	–	0.7	V
			2.7 to 3.6	–	–	0.8	V
			4.5 to 5.5	–	–	0.3 × V _{CC}	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} I _O = 100 μA	1.65 to 5.5	–	–	0.1	V
		I _O = 4 mA	1.65	–	–	0.45	V
		I _O = 8 mA	2.3	–	–	0.3	V
		I _O = 12 mA	2.7	–	–	0.4	V
		I _O = 24 mA	3.0	–	–	0.55	V
		I _O = 32 mA	4.5	–	–	0.55	V
I _{LI}	input leakage current	V _I = 5.5 V or GND	1.65 to 5.5	–	±0.1	±5	μA
I _{OZ}	output OFF-state current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND	5.5	–	±0.1	±10	μA
I _{off}	power OFF leakage current	V _I or V _O = 5.5 V	0	–	±0.1	±10	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0 A	5.5	–	0.1	10	μA
ΔI _{CC}	additional quiescent supply current per pin	V _I = V _{CC} – 0.6 V; I _O = 0 A	2.3 to 5.5	–	5	500	μA

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SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V _{CC} (V)				
T_{amb} = -40 °C to +125 °C							
V _{IH}	HIGH-level input voltage		1.65 to 1.95	0.65 × V _{CC}	–	–	V
			2.3 to 2.7	1.7	–	–	V
			2.7 to 3.6	2.0	–	–	V
			4.5 to 5.5	0.7 × V _{CC}	–	–	V
V _{IL}	LOW-level input voltage		1.65 to 1.95	–	–	0.35 × V _{CC}	V
			2.3 to 2.7	–	–	0.7	V
			2.7 to 3.6	–	–	0.8	V
			4.5 to 5.5	–	–	0.3 × V _{CC}	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} I _O = 100 μA	1.65 to 5.5	–	–	0.1	V
		I _O = 4 mA	1.65	–	–	0.70	V
		I _O = 8 mA	2.3	–	–	0.45	V
		I _O = 12 mA	2.7	–	–	0.60	V
		I _O = 24 mA	3.0	–	–	0.80	V
		I _O = 32 mA	4.5	–	–	0.80	V
I _{LI}	input leakage current	V _I = 5.5 V or GND	1.65 to 5.5	–	–	±20	μA
I _{OZ}	output OFF-state current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND	5.5	–	–	±10	μA
I _{off}	power OFF leakage current	V _I or V _O = 5.5 V	0	–	–	±20	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0 A	5.5	–	–	40	μA
ΔI _{CC}	additional quiescent supply current per pin	V _I = V _{CC} – 0.6 V; I _O = 0 A	2.3 to 5.5	–	–	5000	μA

Note

1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

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AC CHARACTERISTICS

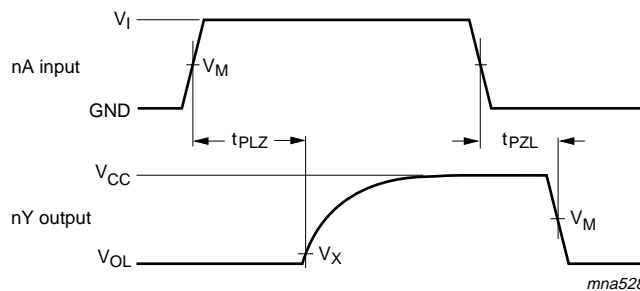
GND = 0 V.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	V _{CC} (V)				
T_{amb} = -40 °C to +85 °C; note 1							
t _{PLZ} /t _{PZL}	propagation delay input nA to output nY	see Figs 5 and 6	1.65 to 1.95	1.0	3.5	6.7	ns
			2.3 to 2.7	0.5	2.4	4.3	ns
			2.7	1.0	2.3	4.2	ns
			3.0 to 3.6	0.5	2.6	3.7	ns
			4.5 to 5.5	0.5	1.5	2.9	ns
T_{amb} = -40 °C to +125 °C							
t _{PLZ} /t _{PZL}	propagation delay input nA to output nY	see Figs 5 and 6	1.65 to 1.95	1.0	3.5	8.4	ns
			2.3 to 2.7	0.5	2.4	5.5	ns
			2.7	1.0	2.3	5.3	ns
			3.0 to 3.6	0.5	2.6	4.7	ns
			4.5 to 5.5	0.5	1.5	3.7	ns

Note

1. All typical values are measured at T_{amb} = 25 °C and at V_{CC} = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

AC WAVEFORMS



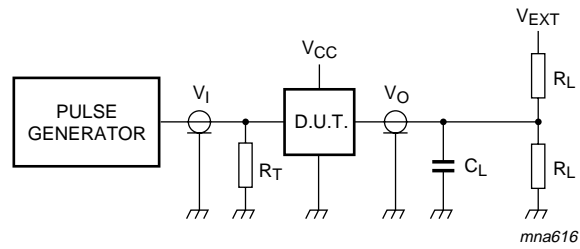
V _{CC}	V _M	V _X	INPUT	
			V _I	t _r = t _f
1.65 V to 1.95 V	0.5 × V _{CC}	V _{OL} + 0.15 V	V _{CC}	≤ 2.0 ns
2.3 V to 2.7 V	0.5 × V _{CC}	V _{OL} + 0.15 V	V _{CC}	≤ 2.0 ns
2.7 V	1.5 V	V _{OL} + 0.3 V	2.7 V	≤ 2.5 ns
3.0 V to 3.6 V	1.5 V	V _{OL} + 0.3 V	2.7 V	≤ 2.5 ns
4.5 V to 5.5 V	0.5 × V _{CC}	V _{OL} + 0.3 V	V _{CC}	≤ 2.5 ns

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.5 Input nA to output nY propagation delays.

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V _{CC}	V _I	C _L	R _L	V _{EXT}
				t _{PZL} /t _{PLZ}
1.65 V to 1.95 V	V _{CC}	30 pF	1 kΩ	2 × V _{CC}
2.3 V to 2.7 V	V _{CC}	30 pF	500 Ω	2 × V _{CC}
2.7 V	2.7 V	50 pF	500 Ω	6 V
3.0 V to 3.6 V	2.7 V	50 pF	500 Ω	6 V
4.5 V to 5.5 V	V _{CC}	50 pF	500 Ω	2 × V _{CC}

Definitions for test circuit:

R_L = Load resistor.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig.6 Load circuitry for switching times.

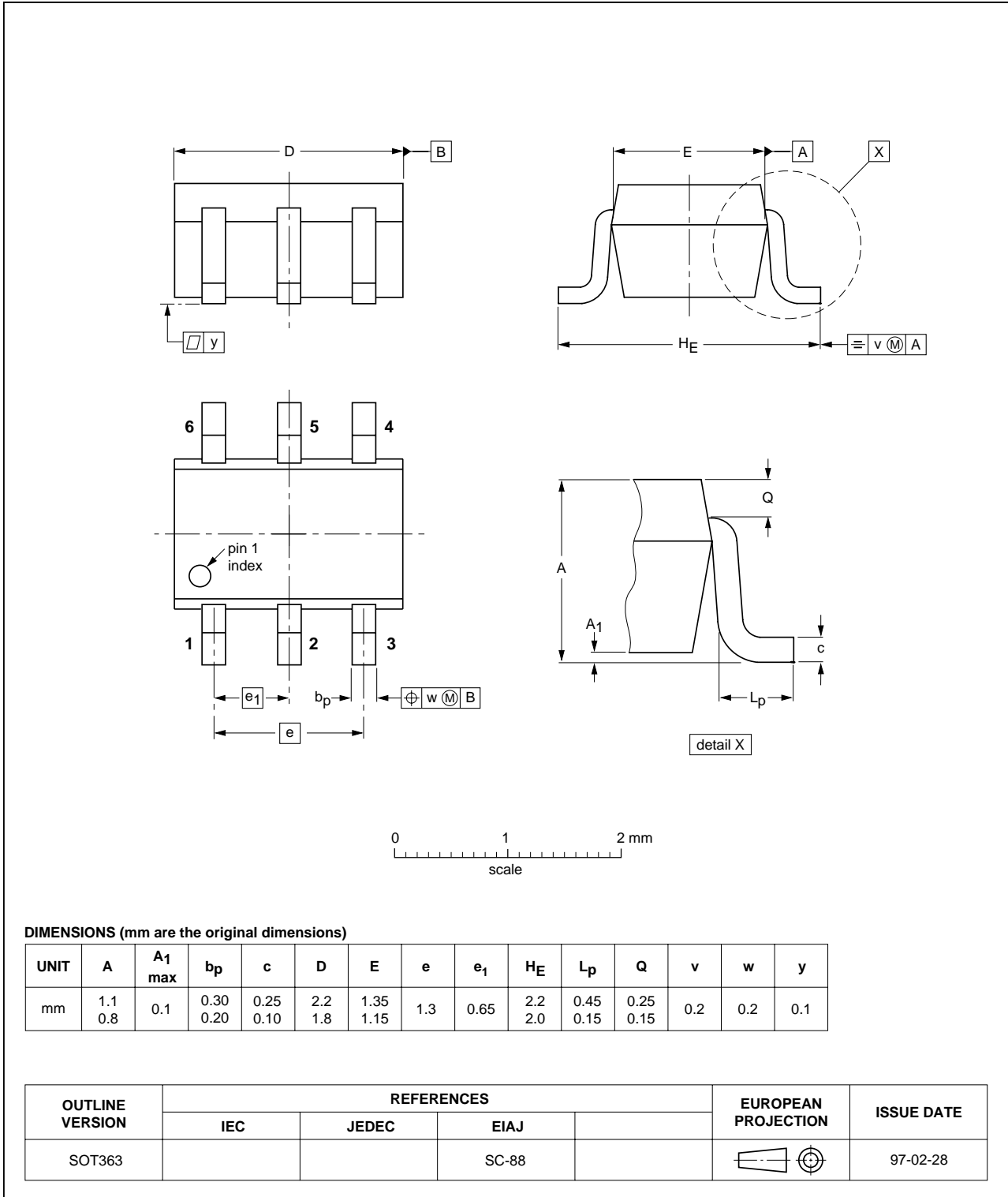
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PACKAGE OUTLINES

Plastic surface mounted package; 6 leads

SOT363

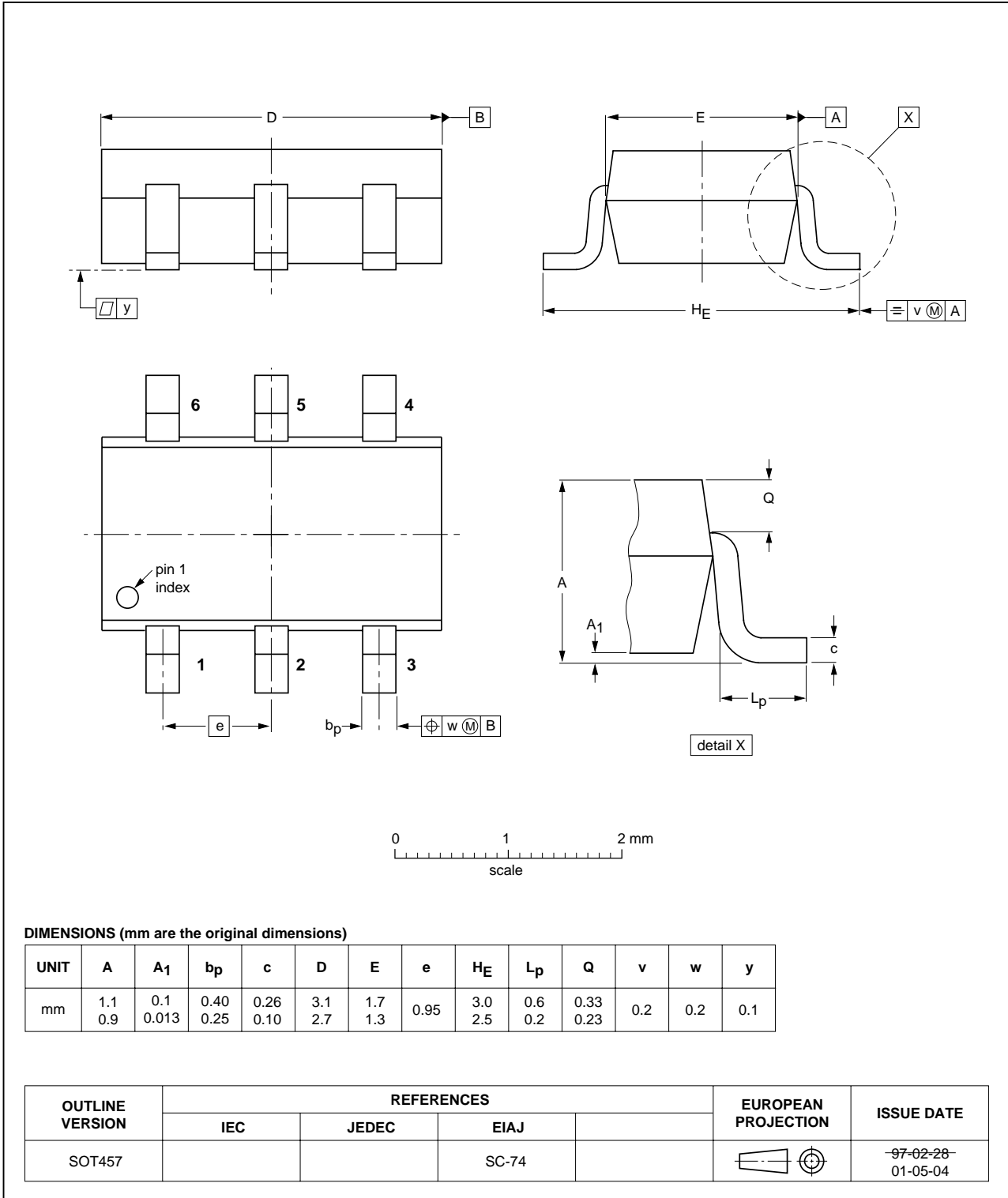


Buffers with open-drain outputs

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Plastic surface mounted package; 6 leads

SOT457

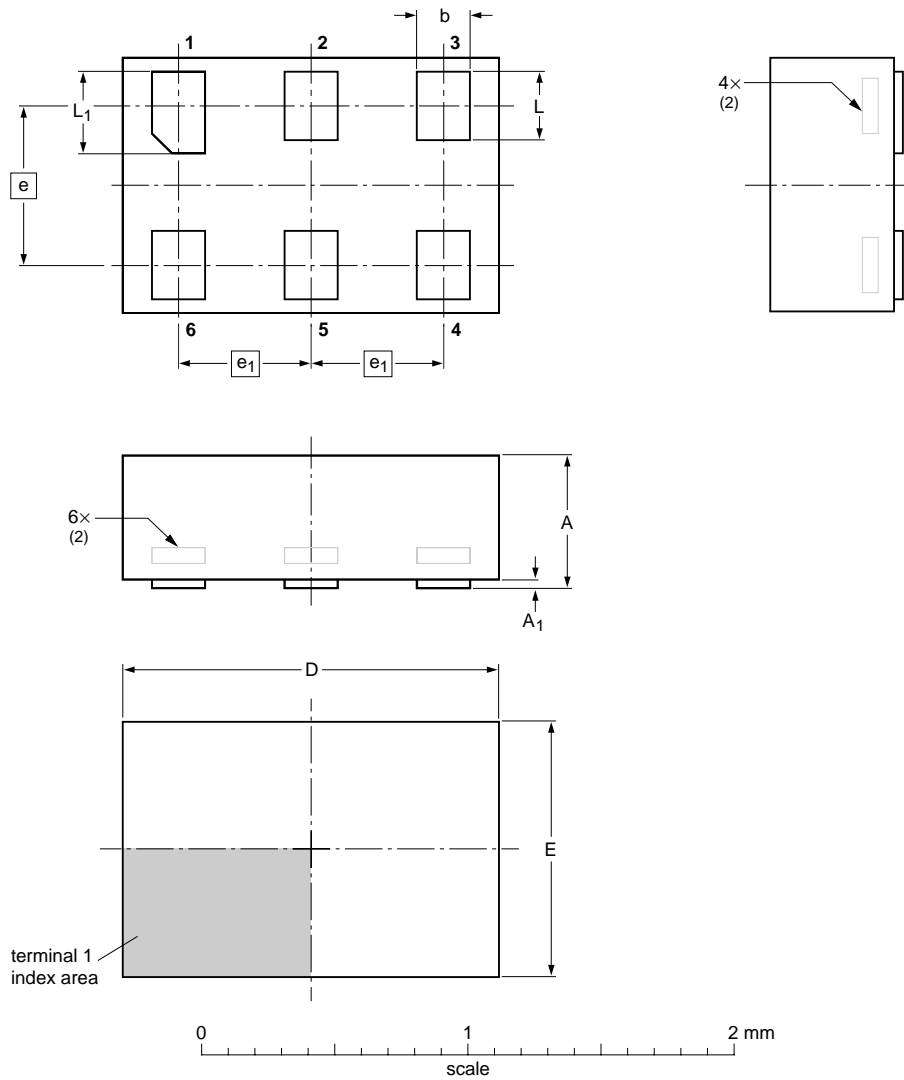


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XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max	A ₁ max	b	D	E	e	e ₁	L	L ₁
mm	0.5	0.04	0.25 0.17	1.5 1.4	1.05 0.95	0.6	0.5	0.35 0.27	0.40 0.32

Notes

1. Including plating thickness.
2. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT886		MO-252			04-07-15 04-07-22

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
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